

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1025885	(insulat\$3 dielectric)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 12:20
L3	918841	1 and (via hole contact groove recess open\$3)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 12:14
L4	473594	3 and temperature	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 12:14
L5	95315	4 and stress	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 11:30
L6	25493	5 and (thermal near5 expansion)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 12:15
L7	395	6 and (elastic near5 coefficient)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 12:16
L9	20	7 and (poisson near5 ratio)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 11:32
L10	1115434	(insulat\$3 dielectric)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/01 12:14
L11	392735	10 and (via hole contact groove recess open\$3)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/01 12:14
L12	40185	11 and temperature	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/01 12:14
L13	1222	12 and (thermal and expansion)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/01 12:15
L14	1006	13 and (thermal near5 expansion)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/01 12:15
L15	1222	13 14	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/01 12:15

L16	15	15 and (elastic and coefficient)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/07/01 12:16
L17	124	1 and (thermal near5 coefficient near5 wir\$3 near5 layer)	US-PGPU B; USPAT; USOCR	OR	ON	2005/07/01 12:21